

P-Channel Enhancement Mode MOSFET

1. Product Information

Features

- Advanced Trench Technology
- Excellent $R_{DS(ON)}$
- Low Gate Charge

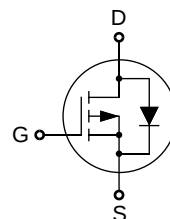
Applications

- PWM Applications
- Load Switch

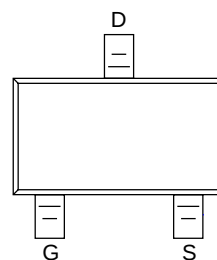
Quick reference

- $V_{DS} = -30\text{ V}$
- $I_D = -4.2\text{ A}$
- $P_D = 1.4\text{ W}$
- $R_{DS(ON)} \leq 60\text{ m}\Omega @ V_{GS}=10\text{ V}$ (Type: 47 m Ω)
- $R_{DS(ON)} \leq 85\text{ m}\Omega @ V_{GS}=4.5\text{ V}$ (Type: 65 m Ω)

Schematic Diagram



Pin Assignment



SOT23-3L

Package Marking and Ordering Information

Product Name	Package	Marking	Reel Size	Tape Width	Quantity(pcs)
KJ3407A	SOT23-3L	3407	7 inch	8 mm	3000

2. Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Values	Unit
V_{DS}	Drain-Source Voltage	-30	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current	-4.2	A
I_{DM}	Pulsed Drain Current ¹	-16	A
P_D	Power Dissipation ²	1.4	W
E_{AS}	Single Pulse Avalanche Energy	2000	mJ
I_{AS}	Avalanche Current	20	A
E_{AR}	Repetitive Avalanche Energy	8	mJ
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55~150	$^\circ\text{C}$
$R_{\theta JA}$	Thermal Resistance from Junction to Ambient ^{3, 4}	125	$^\circ\text{C/W}$
$R_{\theta JL}$	Thermal Resistance from Junction to Lead	80	$^\circ\text{C/W}$

3. Electrical Characteristics (T_J=25°C, unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
OFF Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0 V, I _D =-250 μA	-30		-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-30 V, V _{GS} =0 V	-	-	-1	μA
I _{GSS}	Gate-Source Leakage	V _{DS} =0 V, V _{GS} =±20 V	-	-	±100	nA
ON Characteristics						
V _{GS(th)}	Gate-Threshold Voltage	V _{DS} =V _{GS} , I _D =-250 μA	-1.0	-1.5	-2.0	V
R _{DS(ON)}	Drain-Source On-Resistance	V _{GS} =-10 V, I _D =-4.2 A	-	47	60	mΩ
		V _{GS} =-4.5 V, I _D =-3 A	-	65	85	
G _{FS}	Forward transconductance	V _{DS} =-5 V, I _D =-1 A	-	10	-	S
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =-10 V, V _{GS} =0 V, f=1.0 MHz	-	583	-	pF
C _{oss}	Output Capacitance		-	100	-	
C _{rss}	Reverse Transfer Capacitance		-	80	-	
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DS} =-15 V, V _{GS} =-10 V, R _G =25 Ω, R _L =3.6 Ω, I _D =-4.2 A	-	2.8	-	ns
t _r	Turn-on Rise Time		-	8.4	-	
t _{d(off)}	Turn-off Delay Time		-	39	-	
t _f	Turn-off Fall Time		-	6	-	
Q _g	Total Gate Charge	V _{DS} =-15, V _{GS} =0 V, I _D =-4.2 A	-	6.4	-	nC
Q _{gs}	Gate-Source Charge		-	2.3	-	
Q _{gd}	Gate-Drain Charge		-	1.9	-	
Drain-Source Diode Characteristics						
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =-4.2 A, V _{GS} =0 V	-	-0.81	-1.2	V

Notes:

1. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C. Ratings are based on low frequency and duty cycles to keep initial T_J=25°C.
2. The power dissipation P_D is based on T_{J(MAX)}=150°C, using ≤ 10 s junction-to-ambient thermal resistance.
3. The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2 oz. Copper, in a still air environment with T_A=25°C. The value in any given application depends on the user's specific board design.
4. The R_{θJA} is the sum of the thermal impedance from junction to lead R_{θJL} and lead to ambient.

4. Typical Characteristics

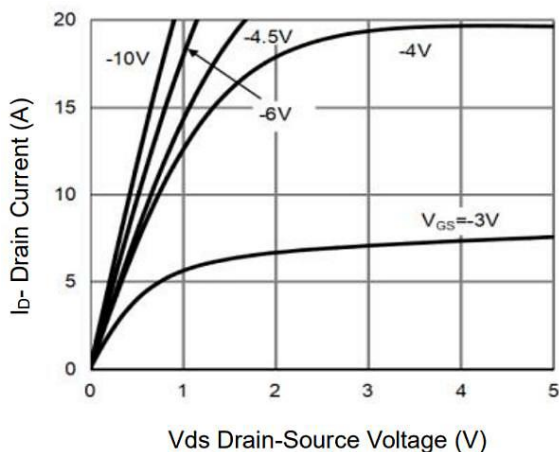


Figure 1. Output Characteristics

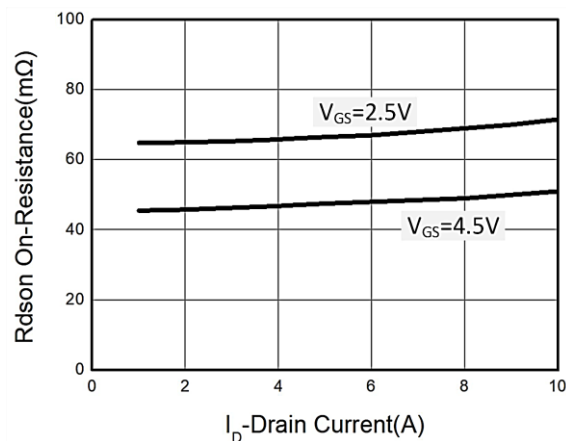


Figure 2. On-Resistance vs. Drain Current

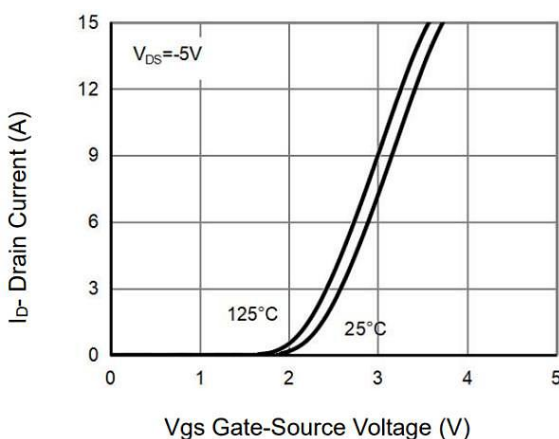


Figure 3. Transfer Characteristic

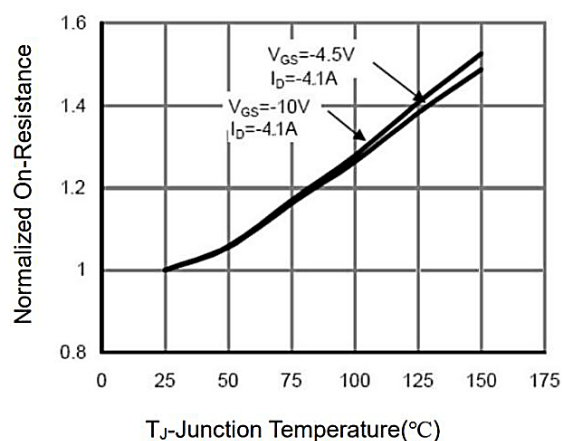


Figure 4. On-Resistance vs. Junction Temperature

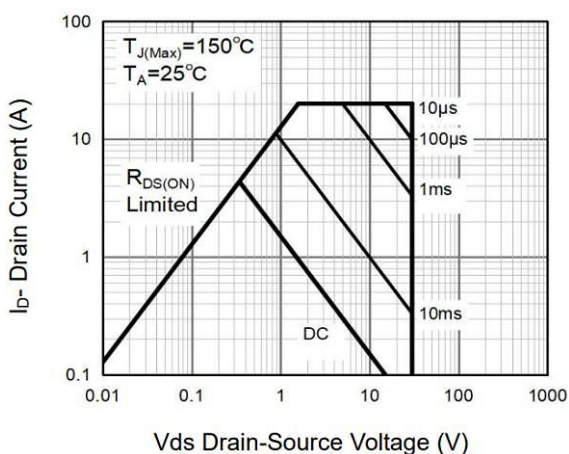


Figure. 5 Safe Operation Area

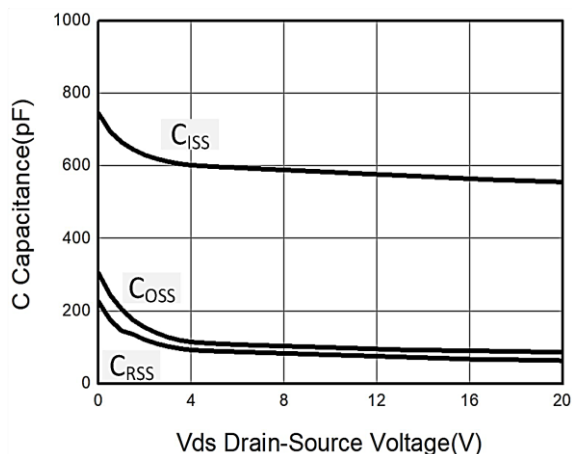


Figure. 6 Capacitance Characteristic

4. Typical Characteristics (Cont.)

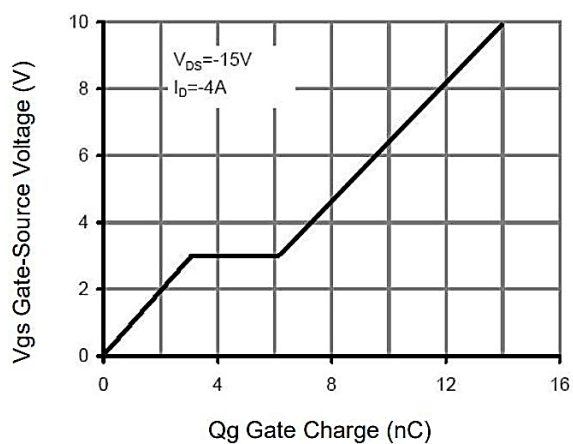


Figure. 7 Gate-Charge Characteristic

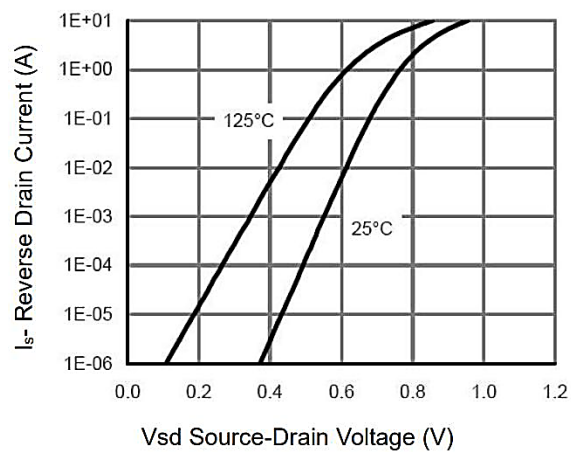
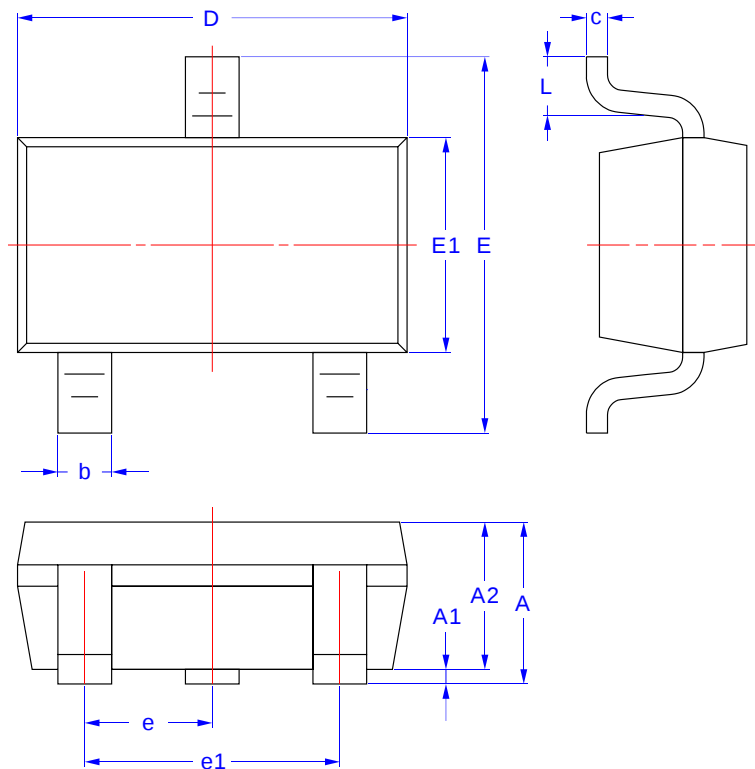


Figure. 8 Body Diode Characteristic

5. Package Mechanical Data

SOT23-3L Package



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	1.00	1.45
A1	0.00	0.15
A2	1.00	1.30
D	2.70	3.10
E	2.60	3.00
E1	1.50	1.70
c	0.08	0.25
b	0.30	0.50
e	0.95 BSC	
e1	1.90 BSC	
L	0.30	0.60